

BY448GP

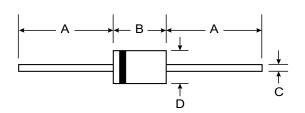
2.0A Axial Leaded Sintered Class Junction Plastic Rectifier

Features

- High temperature metallurgically bonded construction
- Sintered glass cavity free junction
- Capability of meeting environmental standard of MIL-S-19500
- High temperature soldering guaranteed 350°C /10sec/0.375"lead length at 5 lbs tension
- Operate at Ta =55°C with no thermal run away
- Typical Ir<0.1μA

Mechanical Data

- Terminal:Plated axial leads solderable per MIL-STD 202E, method 208C
- Case:Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy
- Polarity:color band denotes cathode
- Mounting position:any



DO-15				
Dim	Min Max			
Α	25.40	_		
В	5.50	7.62		
С	0.686	0.889		
D	2.60	3.60		
All Dimensions in mm				

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

		SYMBOL	BY448GP	units
Maximum Recurrent Peak Reverse Voltage	je	Vrrm	1650	V
Maximum RMS Voltage		Vrms	1150	V
Maximum DC blocking Voltage		Vdc	1650	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta =55°C		If(av)	2.0	А
Peak Forward Surge Current 8.3ms single Half sine-wave superimposed on rated load		Ifsm	30.0	А
Maximum Instantaneous Forward Voltage at 3.0A		Vf	1.60	V
Maximum full load reverse current full cyc Average at 55°C	e	Ir(av)	100.0	μΑ
Maximum DC Reverse Current at rated DC blocking voltage	Ta =25°C Ta =150°C	Ir	5.0 150.0	μA μA
Typical Reverse Recovery Time	(Note 1)	Trr	1000	nS
Typical Thermal Resistance	(Note 2)	Rth(ja)	100	K/W
Storage and Operating Junction Tempera	ture	Tstg, Tj	-65 to +175	°C

Note:

- 1. Reverse Recovery Condition If =0.5A, Ir =1.0A, Irr =0.25A
- 2. Thermal Resistance from Junction to Ambient on PC board with spacing 25mm



